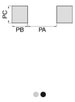
Multilayer Ceramic Chip Capacitors

CGB3B1X5R1A475K055AC

TDK item description	CGB3B1X5R1A475K1****
Applications	Commercial Grade
Feature	LowP Low Profile
Series	CGB3(1608) [EIA:0603]
Status	Production (Not Recommended for New Design)
Brand	TDK



Images are for reference only and show example products.

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Characterization Sheet
Sample Kits
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S-parameter
SPICE Netlist (Simple)
SPICE Netlist (Precision)
Equivalent Circuit Model Update
DC Bias / Superimposition Model (HSpice)
DC Bias / Superimposition Model (LTSpice)
DC Bias / Superimposition Model (PSpice) Update

Size

Length(L)	1.60mm ±0.10mm
Width(W)	0.80mm ±0.10mm
Thickness(T)	0.50mm ±0.05mm
Terminal Width(B)	0.20mm Min.
Terminal Spacing(G)	0.30mm Min.
Recommended Land Pattern (PA)	0.70mm to 1.00mm(Flow Soldering) 0.60mm to 0.80mm(Reflow Soldering)
Recommended Land Pattern (PB)	0.80mm to 1.00mm(Flow Soldering) 0.60mm to 0.80mm(Reflow Soldering)
Recommended Land Pattern (PC)	0.60mm to 0.80mm(Flow Soldering) 0.60mm to 0.80mm(Reflow Soldering)

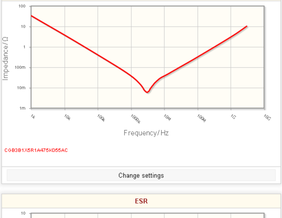
Electrical Characteristics

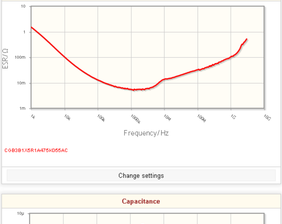
Capacitance	4.7μF ±10%
Rated Voltage	10VDC
Temperature Characteristic	X5R(±15%)
Dissipation Factor (Max.)	10%
Insulation Resistance (Min.)	21MΩ

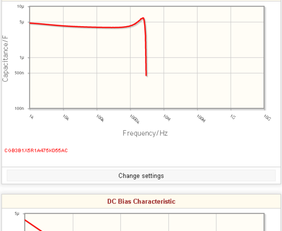
Other

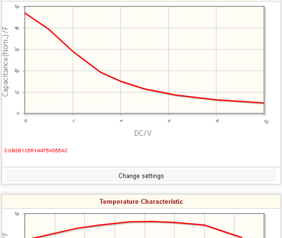
Soldering Method	Wave (Flow) Reflow
AEC-Q200	NO
Packing	Punched (Paper)Taping [180mm Reel]
Package Quantity	4000pcs

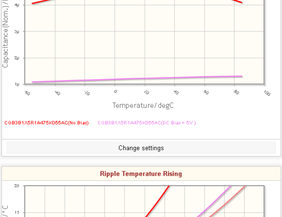
Characteristic Graph (This is reference data, and does not guarantee the products characteristics.)

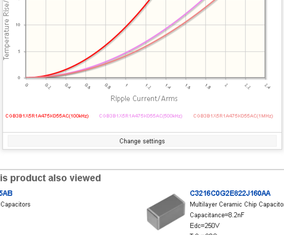












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C2012X7S2A334K125AB
Multilayer Ceramic Chip Capacitors
Capacitance=0.33μF
Edc=100V
T.C.=X7S
LxWxT:2.1x1.25x1.25mm
Mid Volt. (100 to 630V)

C3216C0G2E822J160AA
Multilayer Ceramic Chip Capacitors
Capacitance=8.2nF
Edc=250V
T.C.=C0G
LxWxT:3.2x1.6x1.6mm
Mid Volt. (100 to 630V)

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